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<ul> <li>Members of the Texas Instruments Widebus<sup>™</sup> Family</li> </ul>	SN54ABT162501 WD PACKAGE SN74ABT162501 DGG OR DL PACKAGE (TOP VIEW)				
<ul> <li>B-Port Outputs Have Equivalent 25-Ω</li> </ul>					
Series Resistors, So No External Resistors	OEAB	$\bigcup_{56}$	] GND		
Are Required			] CLKAB		
● State-of-the-Art EPIC-IIB <sup>™</sup> BiCMOS Design	A1 [] 3		] B1		
Significantly Reduces Power Dissipation			] GND		
● UBT <sup>™</sup> (Universal Bus Transceiver)	A2 🛛 5		] B2		
Combines D-Type Latches and D-Type	A3 🛛 6		] B3		
Flip-Flops for Operation in Transparent,	V <sub>CC</sub> [ 7	50	] v <sub>cc</sub>		
Latched, or Clocked Mode	A4 [ 8		] B4		
<ul> <li>Typical V<sub>OLP</sub> (Output Ground Bounce)</li> </ul>	A5 🛛 9	48	] B5		
< 0.8 V at $V_{CC}$ = 5 V, T <sub>A</sub> = 25°C	A6 🚺 10	47	] B6		
High-Impedance State During Power Up	GND [ 11	46	] GND		
and Power Down	A7 🛛 12	45	] B7		
• Flow-Through Architecture Optimizes PCB	A8 🛛 13		B8		
Layout	A9 🛛 14		B9		
•	A10 🛛 15		B10		
<ul> <li>Latch-Up Performance Exceeds 500 mA Per JESD 17</li> </ul>	A11 🛛 16		] B11		
	A12 🛛 17		B12		
ESD Protection Exceeds 2000 V Per	GND 18		] GND		
MIL-STD-883, Method 3015; Exceeds 200 V	A13 [ 19		] B13		
Using Machine Model (C = 200 pF, R = 0)	A14 20		B14		
Package Options Include Plastic Shrink	A15 21		] B15		
Small-Outline (DL) and Thin Shrink	V <sub>CC</sub> 22				
Small-Outline (DGG) Packages and 380-mil	A16 23		] B16		
Fine-Pitch Ceramic Flat (WD) Package	A17 24		] B17		
Using 25-mil Center-to-Center Spacings			] GND		
description	A18 26 OEBA 27		] B18 ] CLKBA		
	LEBA 28				
These 18-bit universal bus transceivers consist of		29	] GND		

These 18-bit universal bus transceivers consist of

storage elements that can operate either as D-type latches or D-type flip-flops to allow data flow in transparent or clocked modes.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B but uses OEBA, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and  $\overline{OEBA}$  is active low).

The B-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.



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#### description (continued)

When  $V_{CC}$  is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

The SN54ABT162501 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74ABT162501 is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

	INPUTS						
OEAB	LEAB	CLKAB	Α	В			
L	Х	Х	Х	Z			
н	Н	Х	L	L			
н	Н	Х	Н	н			
н	L	$\uparrow$	L	L			
н	L	$\uparrow$	Н	н			
н	L	Н	Х	в <sub>0</sub> ‡ во§			
Н	L	L	Х	в <sub>0</sub> §			

FUNCTION TABLE	:†
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<sup>†</sup> A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, and CLKBA.

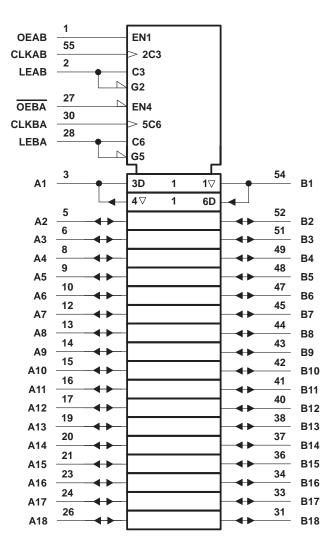
<sup>‡</sup>Output level before the indicated steady-state input conditions were established, provided that CLKAB was high before LEAB went low

§ Output level before the indicated steady-state input conditions were established



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## logic symbol<sup>†</sup>

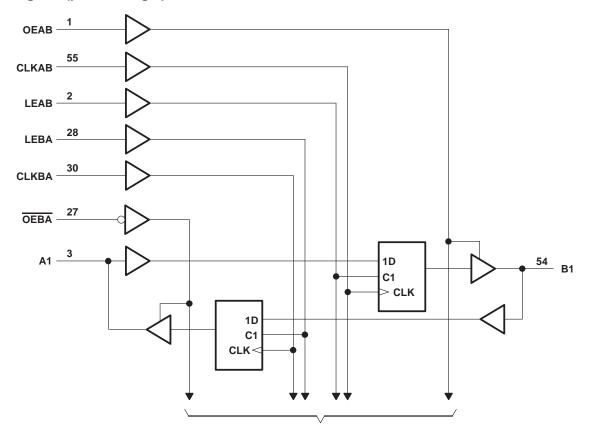


<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



#### SN54ABT162501, SN74ABT162501 **18-BIT UNIVERSAL BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS SCBS243E - SEPTEMBER 1992 - REVISED FEBRUARY 1999

## logic diagram (positive logic)



To 17 Other Channels

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$ Input voltage range, $V_I$ (except I/O ports) (see Note 1) Voltage range applied to any output in the high or power-off state, $V_O$ Current into any output in the low state, $I_O$ : SN54ABT162501 (A port) SN74ABT162501 (A port) B port Input clamp current, $I_{IK}$ ( $V_I < 0$ )	-0.5 V to 7 V -0.5 V to 5.5 V 
Package thermal impedance, $\theta_{JA}$ (see Note 2): DGG package	81°C/W
DL package Storage temperature range, T <sub>stg</sub>	

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed. 2. The package thermal impedance is calculated in accordance with JESD 51.



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## recommended operating conditions (see Note 3)

				162501	SN74ABT	162501	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	VIH High-level input voltage				2		V
VIL	Low-level input voltage					0.8	V
VI	Input voltage	0	Vcc	0	VCC	V	
lau	High-level output current	A port	4	~ -24		-32	mA
ЮН	High-level output current	B port		-12		-12	ma
lai		A port	201	48		64	mA
IOL	Low-level output current B port		0	12		12	mA
$\Delta t / \Delta v$	Input transition rise or fall rate	Outputs enabled	2	10		10	ns/V
Δt/ΔVCC	Power-up ramp rate		200		200		μs/V
Тд	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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## SN54ABT162501, SN74ABT162501 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS243E – SEPTEMBER 1992 – REVISED FEBRUARY 1999

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER VIK		TEOT		Т	A = 25°0	;	SN54ABT	162501	SN74ABT	162501	UNIT
		IESIC	CONDITIONS	MIN	түр†	MAX	MIN	MAX	MIN	MAX	UNIT
		V <sub>CC</sub> = 4.5 V,	lı = –18 mA			-1.2		-1.2		-1.2	V
		V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = –3 mA	2.5			2.5		2.5		
	A	V <sub>CC</sub> = 5 V,	I <sub>OH</sub> = -3 mA	3			3		3		
VOH	A port		I <sub>OH</sub> = -24 mA	2			2				
		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -32 mA	2*					2		v
		V <sub>CC</sub> = 4.5 V,	I <sub>OH</sub> = -1 mA	3.35			3.3		3.35		V
	B port	V <sub>CC</sub> = 5 V,	I <sub>OH</sub> = -1 mA	3.85			3.8		3.85		
	B port	V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = –3 mA	3.1			3		3.1		
		VCC = 4.5 V	I <sub>OH</sub> = -12 mA	2.6					2.6		
	A port	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.55		0.55			
VOL	Apon	VCC = 4.5 V	I <sub>OL</sub> = 64 mA			0.55*				0.55	V
	B port	V <sub>CC</sub> = 4.5 V,	I <sub>OL</sub> = 12 mA			0.8		0.8		0.8	
V <sub>hys</sub>					100			N:			mV
Control inp	Control inputs	V <sub>CC</sub> = 0 to 5.5	V, VI = V <sub>CC</sub> or GND			±1		2 ±1		±1	
II A or B ports		$V_{CC} = 2.1 V$ to $V_I = V_{CC}$ or GN				±20	Tor	±20		±20	μΑ
IOZPU	-	$V_{CC} = 0 \text{ to } 2.1$ $V_{O} = 0.5 \text{ V to } 2$	V, .7 V, OE or OE = X§			±50	DDUGO	±50	50 ±50		μA
IOZPD	I	$V_{CC} = 2.1 V to$ $V_{O} = 0.5 V to 2$	0, .7 V, OE or OE = X§			±50	24	±50		±50	μA
IOZH‡		$\frac{V_{CC}}{OE} = 2.1 \text{ V to}$	5.5 V, V <sub>O</sub> = 2.7 V, $\leq 0.8$ V			10		10		10	μA
Iozl‡		$\frac{V_{CC}}{OE} = 2.1 \text{ V to}$	5.5 V, V <sub>O</sub> = 0.5 V, $\leq 0.8$ V			-10		-10		-10	μA
loff		V <sub>CC</sub> = 0,	$V_{I} \text{ or } V_{O} \le 4.5 \text{ V}$			±100				±100	μA
ICEX	Outputs high	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 5.5 V			50		50		50	μA
	A port	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-110	-180	-50	-180	-50	-180	A
IO <sup>¶</sup>	B port	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-25	-55	-90	-25	-90	-25	-90	mA
		V <sub>CC</sub> = 5.5 V,	Outputs high			3		3		3	
ICC	A or B ports	$I_{O} = 0,$	Outputs low			36		36		36	mA
50		V <sub>I</sub> = V <sub>CC</sub> or GND	Outputs disabled			3		3		3	4
∆ICC <sup>#</sup>			ne input at 3.4 V,			50		50		50	μA
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.			3						pF
Cio	A or B ports	$V_0 = 2.5 V \text{ or } 0$			9						pF

\* On products compliant to MIL-PRF-38535, this parameter does not apply.

<sup>†</sup> All typical values are at  $V_{CC} = 5$  V.

<sup>‡</sup> The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

§ For V<sub>CC</sub> between 2.1 V and 4 V, OE should be less than or equal to 0.5 V to ensure a low state.

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>#</sup>This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

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## SN54ABT162501, SN74ABT162501 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS243E – SEPTEMBER 1992 – REVISED FEBRUARY 1999

# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

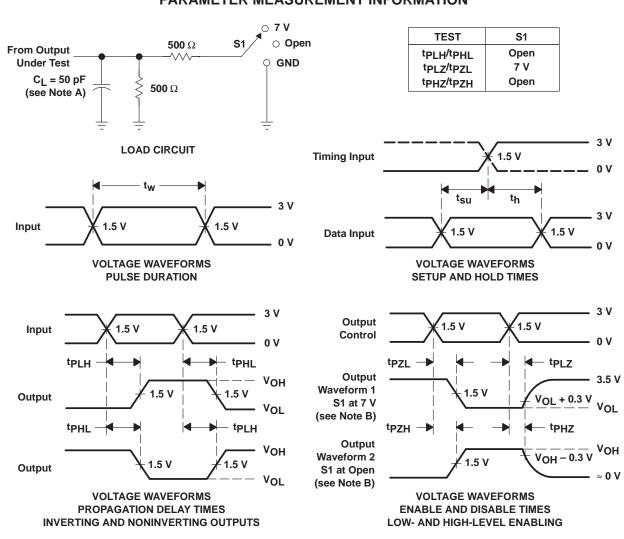
				SN54ABT	162501	SN74ABT162501		UNIT		
				MIN	MAX	MIN	MAX	UNIT		
f <sub>clock</sub> Clock frequency					150		150	MHz		
		LEAB or LEBA high		3	N	3				
tw Pulse duration	CLKAB or CLKBA high or low	CLKAB or CLKBA high or low			;	3.3	N.E	3.3		ns
	A before CLKAB <sup>↑</sup>		4.3	44	4.3					
	Catur time	B before CLKBA <sup>↑</sup>		4.3	r.	4.3				
t <sub>su</sub>	Setup time		CLK high	2.5		2.5		ns		
	A before LEAB $\downarrow$ or B before LEBA $\downarrow$	CLK low	01		1					
t <sub>h</sub> Hold time	A after CLKAB↑ or B after CLKBA↑	A after CLKAB↑ or B after CLKBA↑		<b>Q</b> 0	0					
	A after LEAB $\downarrow$ or B after LEBA $\downarrow$		2		2		ns			

switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V( Tj	CC = 5 V A = 25°C	', ;	SN54ABT	162501	SN74ABT	162501	UNIT
		(001101)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			150	200		150		150		MHz
<sup>t</sup> PLH	A or B	B or A	1.5	2.6	4	1.5	5.1	1.5	4.8	ns
<sup>t</sup> PHL		BUIA	2	3.4	5.2	2	6.1	2	5.7	115
<sup>t</sup> PLH	LEAB or LEBA	B or A	2	3.3	4.8	2	6.1	2	5.6	ns
<sup>t</sup> PHL	LEAD OF LEDA	BUIA	2	3.8	5.2	2 0	6.4	2	5.9	115
<sup>t</sup> PLH		B or A	1.5	3.5	4.7	1.5	6	1.5	5.5	ns
<sup>t</sup> PHL	CLKAB or CLKBA	BUIA	1.5	3.5	4.8	1.5	5.8	1.5	5.3	115
<sup>t</sup> PZH		B or A	1.5	3.4	4.6	A.1.5	5.6	1.5	5.3	
<sup>t</sup> PZL	OEAB or OEBA	BUIA	2	3.8	4.7	2	5.6	2	5.4	ns
<sup>t</sup> PHZ		B or A	2	4.5	5.7	2	6.9	2	6.5	
<sup>t</sup> PLZ	OEAB or OEBA	BUTA	1.5	3.8	5.3	1.5	6.3	1.5	5.8	ns



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns. D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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